

- * Maskdesign
- * Oxidation technologies
- * Characterisation techniques (SEM,AFM, ellipsometry)
- * Design and fabrication of own device

Initial competences

Course physics of technological processes or similar

Final competences

- 1 Safely entering a cleanroom and carrying out research in a cleanroom environment.
- 2 Carry out basic steps for the fabrication of semiconductor devices such as lithography, etching, deposition, bonding.
- 3 Designing a fabrication flow for a photonic device.
- 4 Using advanced mask software for creating gds-files.
- 5 Independently fabricating a semiconductor component.

Conditions for credit contract

Access to this course unit via a credit contract is determined after successful competences assessment

Conditions for exam contract

This course unit cannot be taken via an exam contract

Teaching methods

Practical

Extra information on the teaching methods

Part 1: lab exercises in small groups (2-3 persons), learn basic processing skills (lithography, etching, deposition...)
 Part 2: individual project - design of photonic IC, preparation of processing scheme, processing in cleanroom, characterisation

Learning materials and price

Syllabus (English), elektronik (frees)
 References

References

Course content-related study coaching

Assessment moments

end-of-term and continuous assessment

Examination methods in case of periodic assessment during the first examination period

Oral assessment, Assignment

Examination methods in case of periodic assessment during the second examination period

Assignment

Examination methods in case of permanent assessment

Participation, Assignment

Possibilities of retake in case of permanent assessment

examination during the second examination period is possible in modified form

Extra information on the examination methods

Project is evaluated on the basis of report and oral discussion of report

Calculation of the examination mark

50% lab exercises, 50% project report